

Features

- 0805 size
- Available in E12 Series
- High frequency
- Nickel barrier
- Lead free

Applications

- Mobil phones
- Cellular phones
- CTX, VCR, HIC, FDD
- Automotive electronics



Model CI201210 is currently available, although not recommended for new designs. Use Model CE201210.

CI201210 Series - Multi-Layer Chip Inductors

Electrical Specifications

Bourns Part No.	Inductance		Q	Test Freq.	SRF MHz		DCR	I rms
	nH	Tol. %	min.	L,Q MHz	min.	typ.	ohm max.	mA max.
CI201210-1N0D	1.0	±0.3 nH	10	100	4000	12000	0.10	300
CI201210-1N2D	1.2	±0.3 nH	10	100	4000	10000	0.10	300
CI201210-1N5D	1.5	±0.3 nH	10	100	4000	10000	0.10	300
CI201210-1N8D	1.8	±0.3 nH	10	100	4000	8000	0.10	300
CI201210-2N2D	2.2	±0.3 nH	10	100	3800	8000	0.10	300
CI201210-2N7D	2.7	±0.3 nH	10	100	3600	6000	0.10	300
CI201210-3N3D	3.3	±0.3 nH	10	100	3400	6000	0.13	300
CI201210-3N9D	3.9	±0.3 nH	10	100	3200	5400	0.15	300
CI201210-4N7D	4.7	±0.3 nH	10	100	3000	4500	0.20	300
CI201210-5N6D	5.6	±0.3 nH	10	100	2800	4000	0.23	300
CI201210-6N8J	6.8	±5	10	100	2600	3650	0.25	300
CI201210-8N2J	8.2	±5	10	100	2200	3000	0.28	300
CI201210-10NJ	10	±5	10	100	1800	2500	0.30	300
CI201210-12NJ	12	±5	10	100	1650	2450	0.35	300
CI201210-15NJ	15	±5	10	100	1350	2000	0.40	300
CI201210-18NJ	18	±5	10	100	1350	1750	0.45	300
CI201210-22NJ	22	±5	15	100	1100	1700	0.50	300
CI201210-27NJ	27	±5	15	100	1100	1550	0.55	300
CI201210-33NJ	33	±5	15	100	1000	1350	0.60	300
CI201210-39NJ	39	±5	15	100	900	1300	0.65	300
CI201210-47NJ	47	±5	15	100	850	1200	0.70	300
CI201210-56NJ	56	±5	15	100	750	1150	0.75	300
CI201210-68NJ	68	±5	15	100	400	1000	0.80	300
CI201210-82NJ	82	±5	15	100	600	850	0.90	300
CI201210-R10J	100	±5	15	100	500	730	1.00	300
CI201210-R12J	120	±5	15	50	450	650	1.30	250
CI201210-R15J	150	±5	15	50	400	550	1.50	250
CI201210-R18J	180	±5	15	50	350	500	1.80	250
CI201210-R22J	220	±5	10	50	330	450	2.00	250
CI201210-R27J	270	±5	10	50	300	410	2.50	250
CI201210-R33J	330	±5	10	50	270	370	3.00	250
CI201210-R39J	390	±5	10	50	220	330	3.50	250
CI201210-R47J	470	±5	10	50	180	280	4.00	250

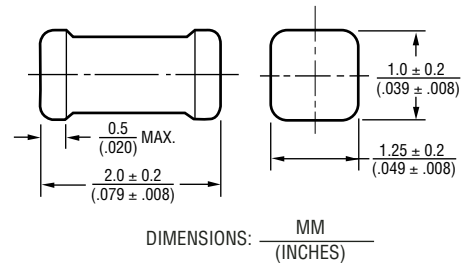
General Specifications

Temperature Rise20 °C max. at rated current
 Operating Temperature ..-55 °C to +125 °C
 Storage Temperature...-55 °C to +125 °C
 Reflow Soldering ...230 °C, 50 sec. max.
 Resistance to Soldering Heat260 °C, 10 seconds

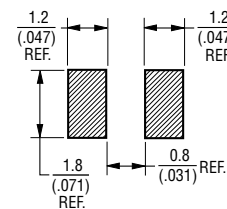
Materials

Base MaterialCeramic
 TerminalAg/Ni/Sn
 Packaging.....3,000 pcs. per reel

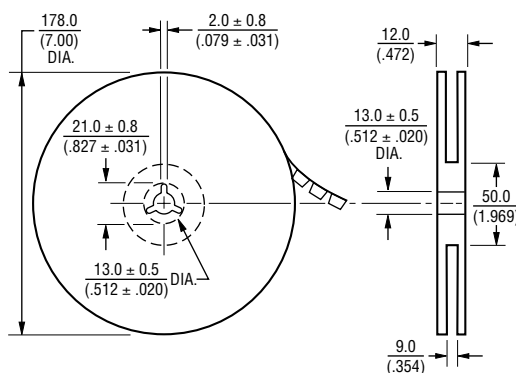
Product Dimensions



Recommended Layout



Packaging Specifications

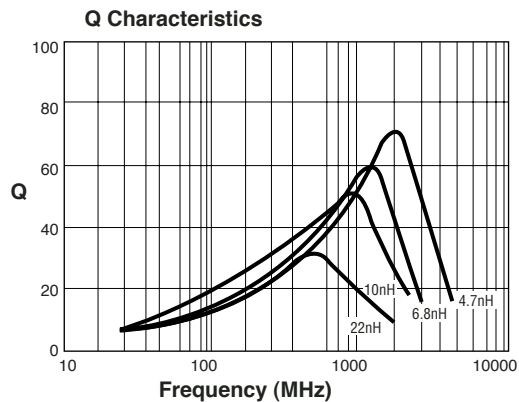
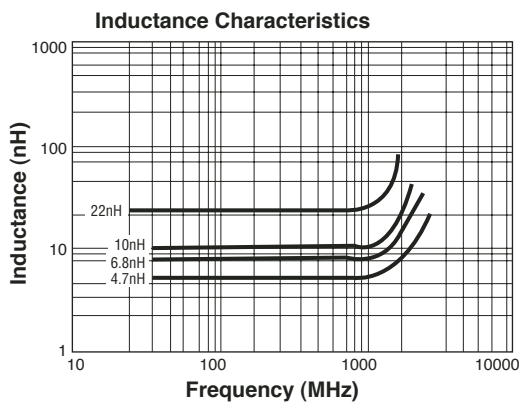


*RoHS Directive 2002/95/EC Jan 27 2003 including Annex Specifications are subject to change without notice. Customers should verify actual device performance in their specific applications.

CI201210 Series - Multi-Layer Chip Inductors

BOURNS®

Electrical Specifications



REV. 05/05

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